



RF360
Europe GmbH

Data sheet

SAW RF downlink filter

Base stations
LTE band 1

Series/type:	B5359
Ordering code:	B39222B5359U410

Date:	June 12, 2019
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Version:	2.1
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A Qualcomm – TDK Joint Venture

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1 Application

- BTS RF TX filter for AWS-3
- Unbalanced to unbalanced operation
- Usable pass band 90 MHz
- No external matching components required

2 Features

- Package code DCC6C
- Package size 3.0 ± 0.1 mm $\times$ 3.0 ± 0.1 mm
- Package height 1.1 ± 0.125 mm
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)

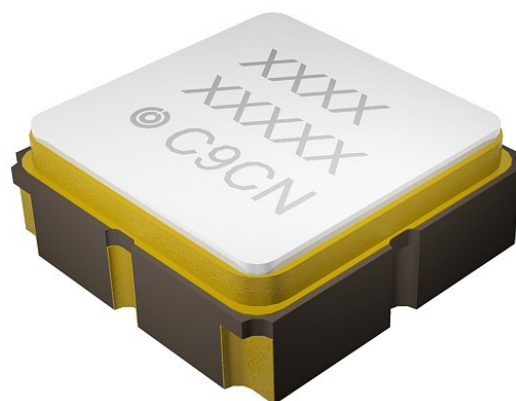
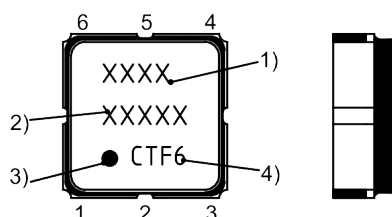


Figure 1: Picture of component with example of product marking.

4 Pin configuration

Technical drawing of a mechanical part. The drawing shows a cross-section of a part with a central hole. The total width of the part is 1.1 ± 0.125. The distance from the left edge to the center of the hole is 0.6. The surface texture symbol indicates a maximum average roughness (Ra) of 0.05.

SIDE VIEW



- 1) Device designation
- 2) Last five digits of the lot number
- 3) Marking for pad number 1
- 4) Example of production location and date code

Diagram illustrating the layout of a 2x3 grid of landing pads. The pads are labeled 1 through 6. The horizontal distance between the centerlines of the pads in the top row is $1.20 \times 2 = 2.40$. The vertical distance between the centerlines of the pads in the left column is 2.25. The width of the pads in the top row is 0.8, and the width of the pads in the bottom row is 0.65. The pads are arranged in two rows and three columns. The pads in the top row are labeled 6, 5, and 4 from left to right. The pads in the bottom row are labeled 1, 2, and 3 from left to right. The pads are arranged in a staggered pattern. The pads are labeled 1 through 6. The horizontal distance between the centerlines of the pads in the top row is $1.20 \times 2 = 2.40$. The vertical distance between the centerlines of the pads in the left column is 2.25. The width of the pads in the top row is 0.8, and the width of the pads in the bottom row is 0.65. The pads are arranged in two rows and three columns. The pads in the top row are labeled 6, 5, and 4 from left to right. The pads in the bottom row are labeled 1, 2, and 3 from left to right. The pads are arranged in a staggered pattern.

Figure 2: Drawing of package. See Sec. Package information (p. 17).

5 Matching circuit

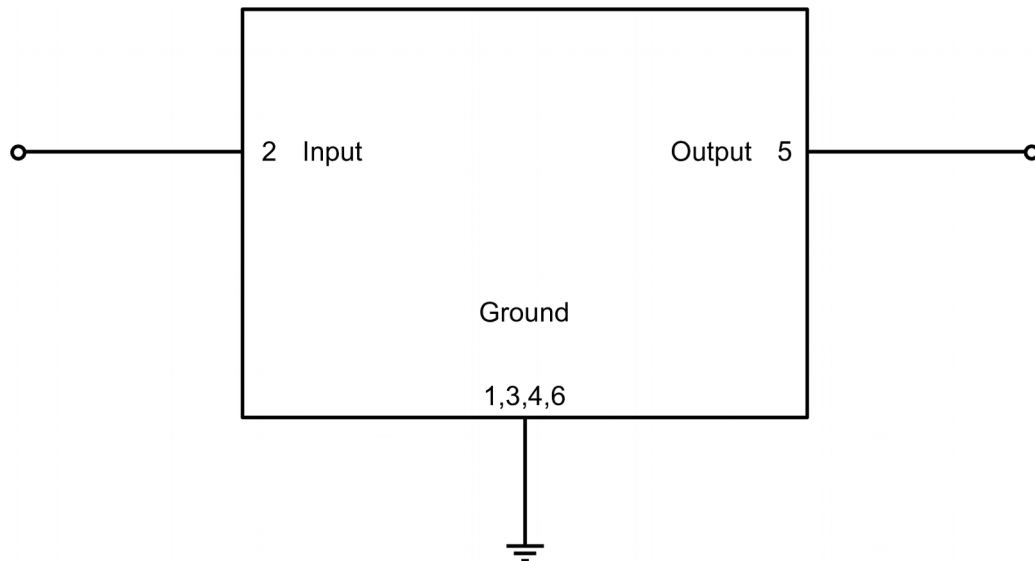


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
Input terminating impedance	Z_{IN}	= 50 Ω
Output terminating impedance	Z_{OUT}	= 50 Ω

Characteristics			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		f_{C}	—	2155	—	MHz
Minimum insertion attenuation	2110... 2200	MHz	α_{min}	1.5	—	dB
Maximum insertion attenuation	2110... 2200	MHz	α_{max}	2.9	3.8	dB
Amplitude ripple (p-p)	2110... 2200	MHz	$\Delta\alpha$	1.0	1.5	dB
Maximum VSWR		VSWR_{max}				
@ input port	2110... 2200	MHz	—	1.6	2.1	
@ output port	2110... 2200	MHz	—	1.6	2.1	
Minimum attenuation (relative to α_{min})		$\alpha_{\text{rel,min}}$				
	50... 1400	MHz	22	34	—	dB
	1400... 1910	MHz	25	36	—	dB
	1910... 1995	MHz	27	40	—	dB
	2300... 3700	MHz	30	37	—	dB
	3700... 4300	MHz	20	30	—	dB
	4300... 5700	MHz	12	26	—	dB

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +125\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +125\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
Input power	P_{IN}	
@ input port: 2110 ... 2200 MHz	24.5 dBm	Continuous wave for 2 h @ 85 °C.
@ input port: 2110 ... 2200 MHz	18 dBm	Continuous wave for 1000 h @ 85 °C.
@ input port: 2110 ... 2200 MHz	13 dBm	Continuous wave for 100000 h @ 85 °C.
@ input port: 2110 ... 2200 MHz	23 dBm	Continuous wave for 2 h @ 105 °C.
@ input port: 2110 ... 2200 MHz	16 dBm	Continuous wave for 1000 h @ 105 °C.
@ input port: 2110 ... 2200 MHz	11 dBm	Continuous wave for 100000 h @ 105 °C.

¹⁾ Not valid for packaging material. Please refer to definition of Shelf life (p. 16).

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficient

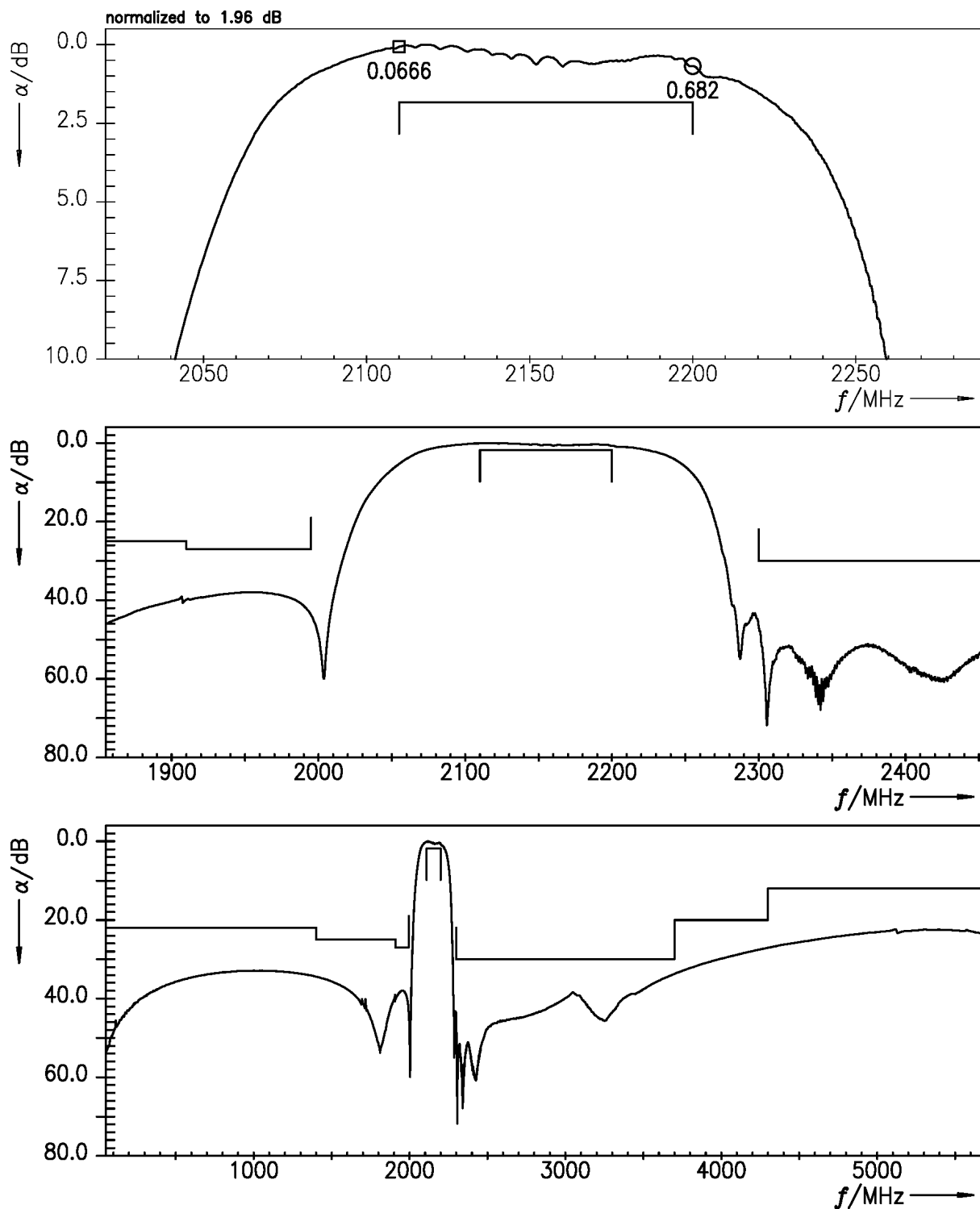


Figure 4: Attenuation.

9 Reflection coefficients

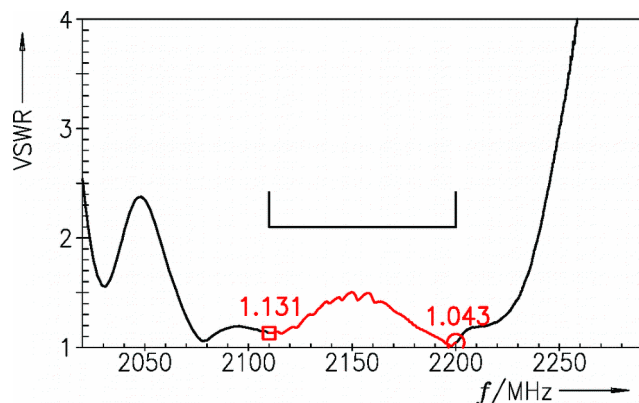


Figure 5: Reflection coefficient at input port.

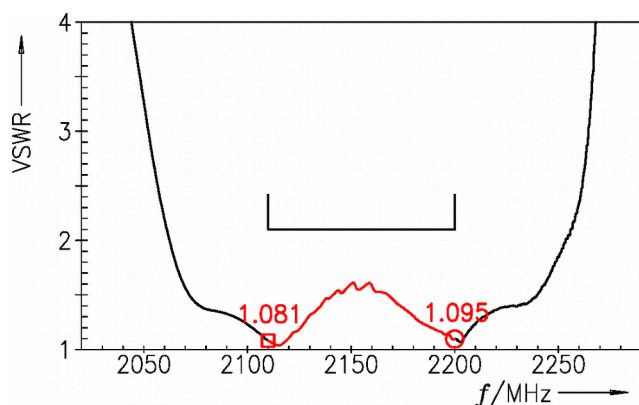
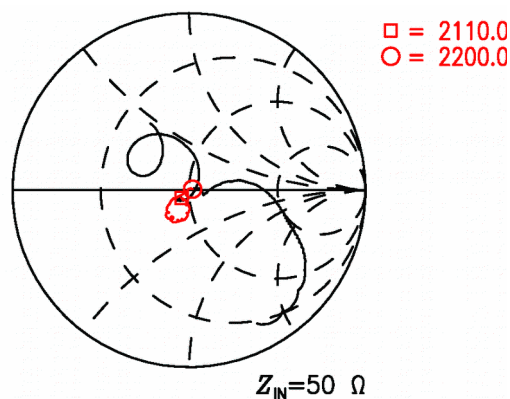
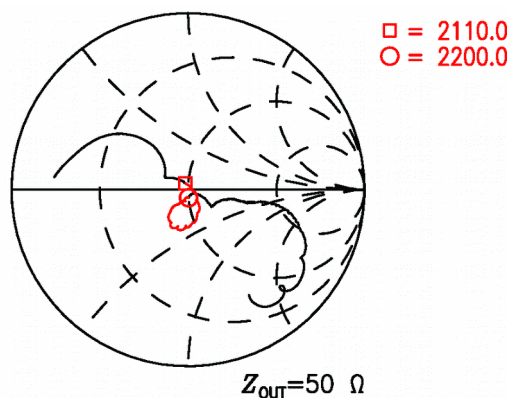


Figure 6: Reflection coefficient at output port.



10 Packing material

10.1 Tape

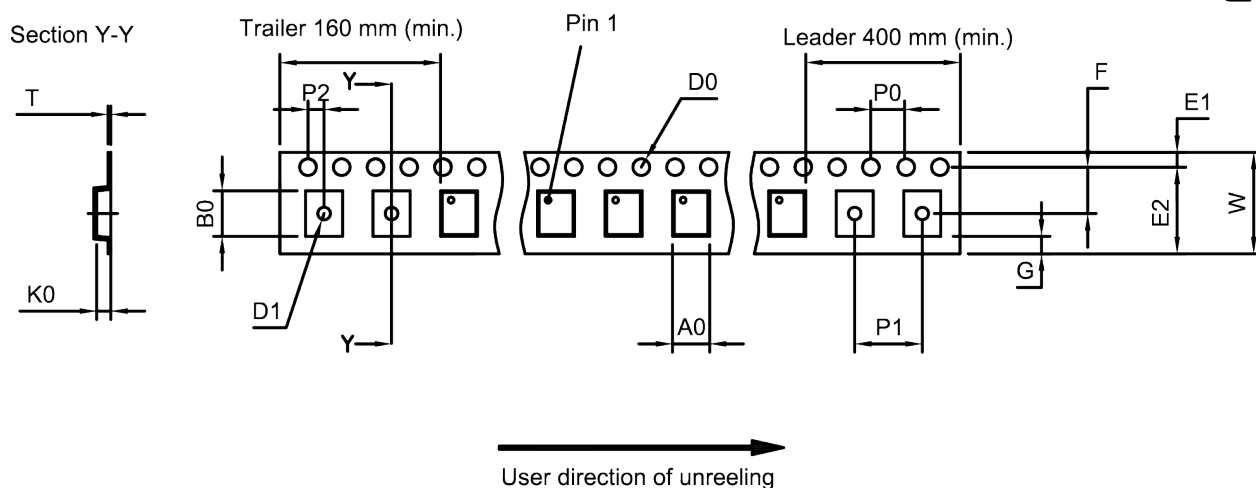


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	3.25±0.1 mm
B ₀	3.3±0.1 mm
D ₀	1.5+0.1/-0 mm
D ₁	1.5 mm (min.)
E ₁	1.75±0.1 mm

E ₂	10.25 mm (min.)
F	5.5±0.05 mm
G	0.75 mm (min.)
K ₀	1.5±0.1 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.1 mm
T	0.3±0.05 mm
W	12.0+0.3/-0.1 mm

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

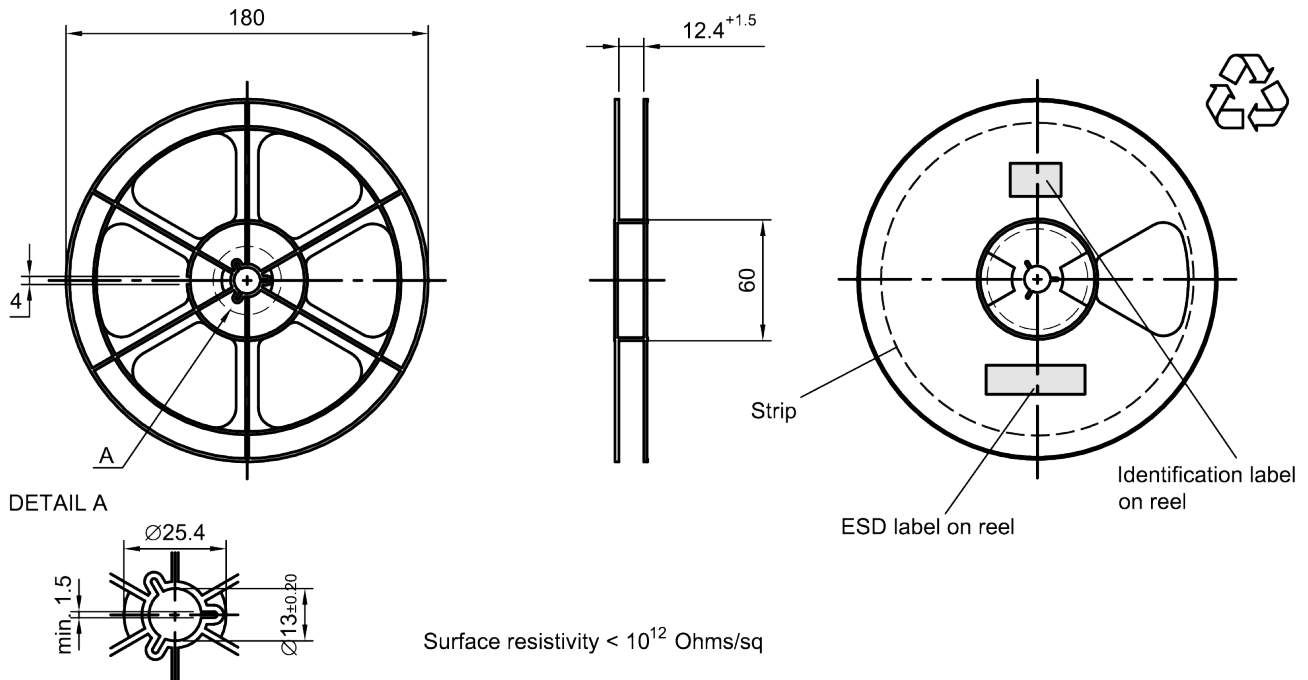


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

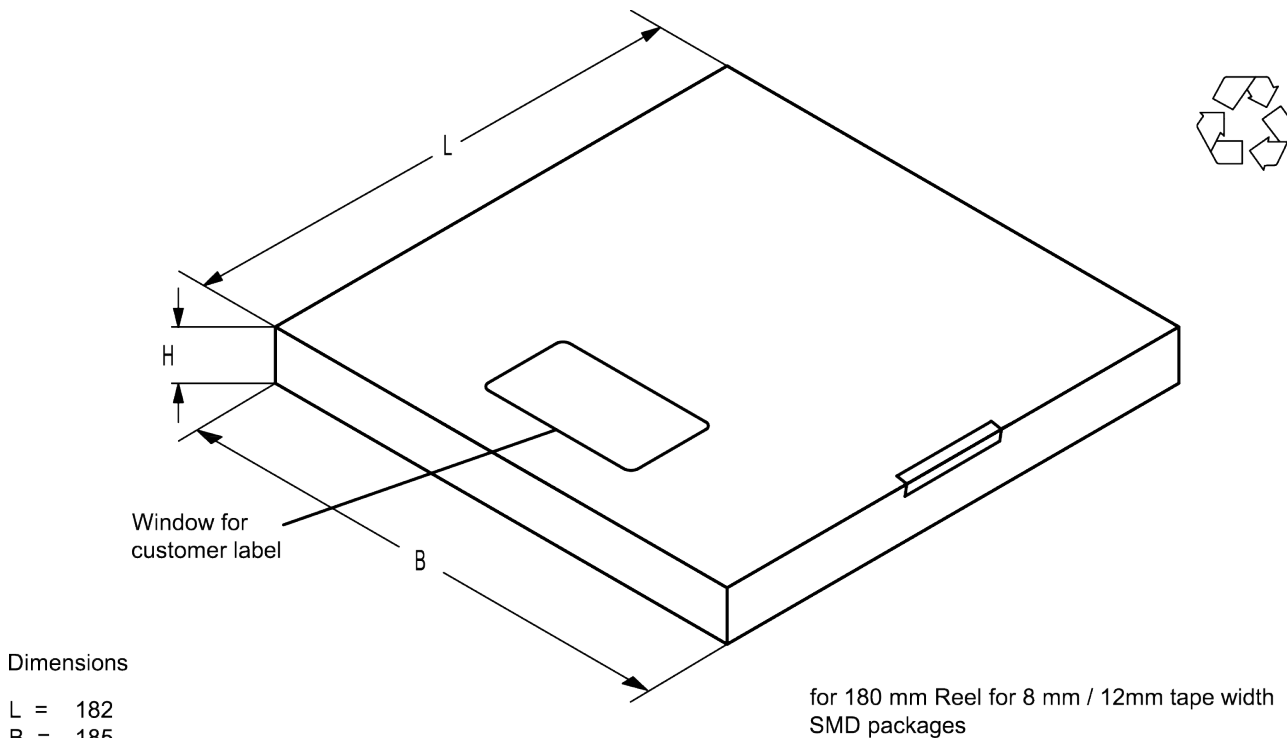


Figure 9: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

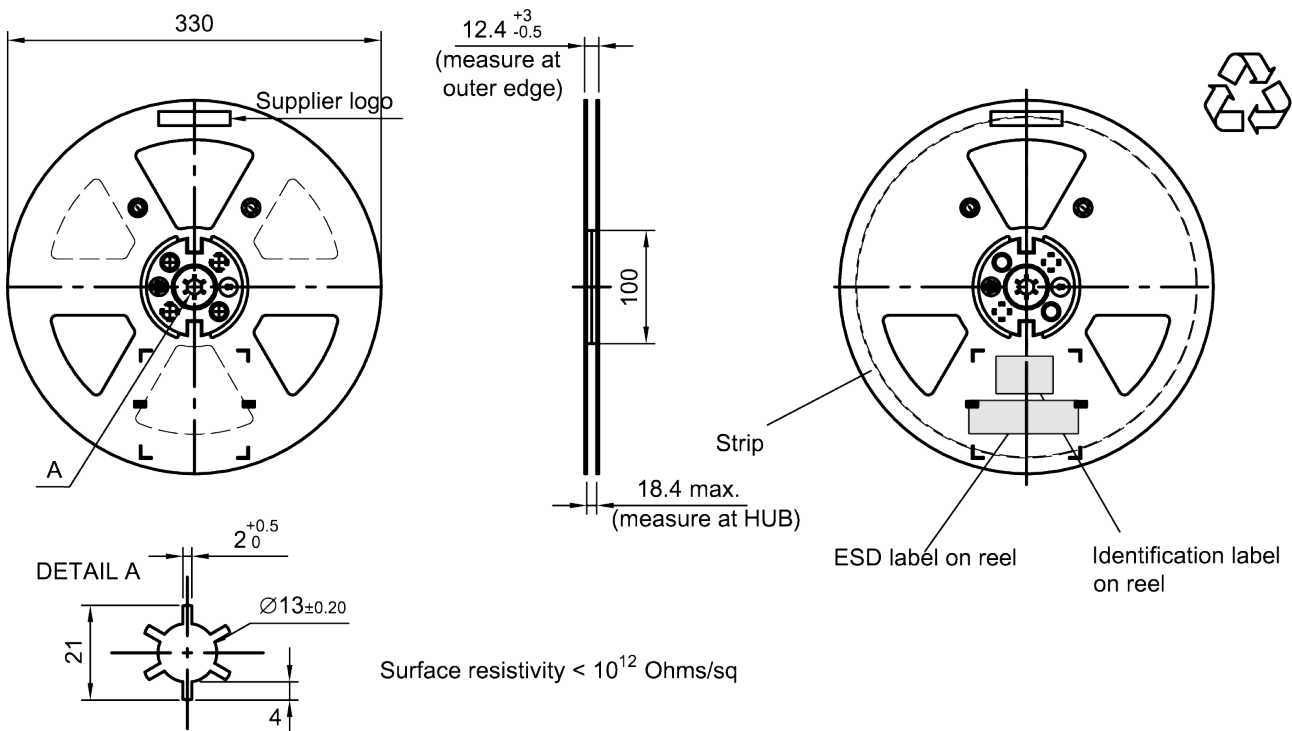


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.

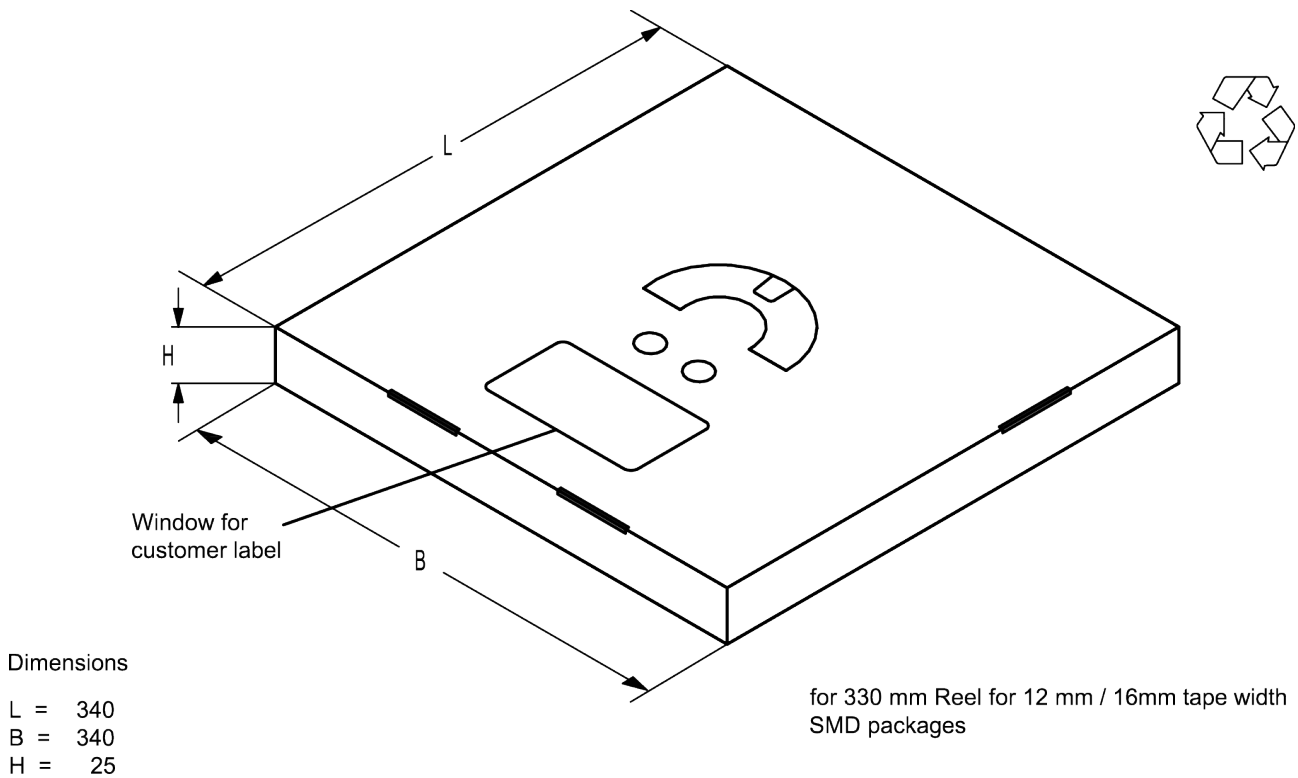


Figure 11: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

- Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

- Lot number: The last 5 digits of the lot number are used for the marking.

Example: 12345

- Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

1 st digit (day)						2 nd digit (year)				3 rd digit (month)			
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	A	21	M	2010	A	2022	P	Jan	1	Jul	7
2	2	12	B	22	N	2011	B	2023	R	Feb	2	Aug	8
3	3	13	C	23	P	2012	C	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	T	Apr	4	Oct	0
5	5	15	E	25	S	2014	E	2026	U	May	5	Nov	N
6	6	16	F	26	T	2015	F	2027	V	Jun	6	Dec	D
7	7	17	H	27	U	2016	H	2028	W				
8	8	18	J	28	V	2017	J	2029	X				
9	9	19	K	29	W	2018	K	2030	Z				
10	0	20	L	30	X	2019	L	2031	A				
				31	Z	2020	M	2032	B				
						2021	N	and so on					

Table 2: Production date code.

Example of how to decode production location and date code:

Code: **C T F 6**

Location: C → Wuxi

Day: T → 26th

Year: F → 2015

Month: 6 → June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220\text{ °C}$	30 s to 70 s
$T > 230\text{ °C}$	min. 10 s
$T > 245\text{ °C}$	max. 20 s
$T \geq 255\text{ °C}$	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

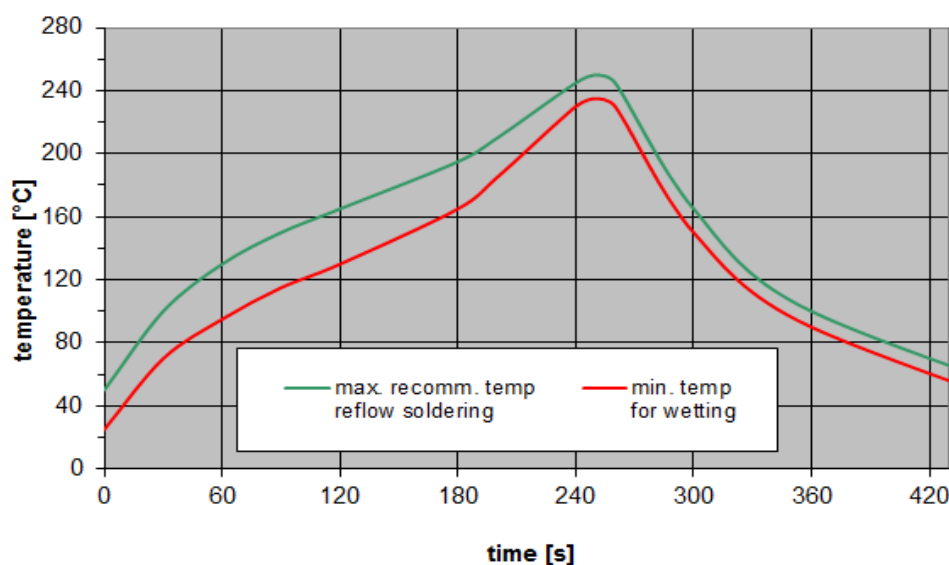


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from $-25\text{ }^{\circ}\text{C}$ to $+40\text{ }^{\circ}\text{C}$, and
- storage humidity with $\leq 75\text{ \% r.h.}$ mean annual humidity, $\leq 95\text{ \% r.h.}$ for max. 30 days / year, and no dew condensation.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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